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Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name	Molex Product Compliance	**E-Mail**	Product.Compliance@molex.com

Part Information

Part Number	0348978240	**Part Weight**	3.657G
Part Name	MINI50 RAHDR SMT 24CKT BLK POL A T&R		

Product Composition

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
MINI50 RAHDR SMT 24CKT BLK POL A T&R	Assembly		100	3.657
MINI50 HSNG RAHDR SMT 24CKT BLK POL A	Component		74.1318	2.711
PS-ST GF30 Black	Material		74.1318	2.711
PS-ST	Substance		43.3229	1.584319
GF-Fibre	Substance		22.3702	0.818077
Pigment portion, not to declare	Substance	system	0.4916	0.017979
Further Additives, not to declare	Substance	system	2.2893	0.083718
Benzene, ethenyl-, polymer with 1,3-butadiene, hydrogenated	Substance	66070-58-4	5.6578	0.206906
MINI50 TERM SMT SOLDER NAIL LT MATTE SN	Component		3.6369	0.133
Cartridge Brass 70% Unplated	Material		3.4181	0.125
Copper	Substance	7440-50-8	2.3927	0.0875
Zinc (metal)	Substance	7440-66-6	1.0254	0.0375
Nickel Plating	Material		0.0766	0.0028

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
Nickel	Substance	7440-02-0	0.0766	0.0028
Further Additives, not to declare	Substance	system	8E-06	3E-07
Tin Plating	Material		0.1422	0.0052
Tin	Substance	7440-31-5	0.1422	0.0052
MINI50 TERM SMT SOLDER NAIL RT MATTE SN	Component		3.4181	0.125
Cartridge Brass 70% Unplated	Material		3.1993	0.117
Copper	Substance	7440-50-8	2.2395	0.0819
Zinc (metal)	Substance	7440-66-6	0.9598	0.0351
Nickel Plating	Material		0.0766	0.0028
Nickel	Substance	7440-02-0	0.0766	0.0028
Further Additives, not to declare	Substance	system	8E-06	3E-07
Tin Plating	Material		0.1422	0.0052
Tin	Substance	7440-31-5	0.1422	0.0052
MINI50 TERM BLD 0.50X15.57 MATTE SN	Component		10.3363	0.378
Cartridge Brass 70% Unplated	Material		9.1879	0.336
Copper	Substance	7440-50-8	6.4315	0.2352
Zinc (metal)	Substance	7440-66-6	2.7564	0.1008
Nickel Plating	Material		0.4594	0.0168
Nickel	Substance	7440-02-0	0.4593	0.016798
Further Additives, not to declare	Substance	system	5E-05	0.000002
Tin Plating	Material		0.6891	0.0252
Tin	Substance	7440-31-5	0.6891	0.0252
MINI50 TERM BLD 0.50X17.77 MATTE SN	Component		8.4769	0.31
Cartridge Brass 70% Unplated	Material		7.6565	0.28
Copper	Substance	7440-50-8	5.3596	0.196
Zinc (metal)	Substance	7440-66-6	2.297	0.084
Nickel Plating	Material		0.3281	0.012
Nickel	Substance	7440-02-0	0.3281	0.011999
Further Additives, not to declare	Substance	system	3E-05	0.000001

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
Tin Plating	Material		0.4922	0.018
Tin	Substance	7440-31-5	0.4922	0.018

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)9139-DC (19 Jan 2021)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead	Cartridge Brass 70% (CA260)	*Note	350	Yes
lead		*Note	500	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes
glass, oxide, chemicals	PS-ST GF30 Black	*Note	320,000	Yes

***Note:** For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Exemptions

Part Name	Exemption
Cartridge Brass 70% (CA260)	44 Concentration within acceptable GADSL limits
	44 Concentration within acceptable GADSL limits
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

None

China ROHS Declaration Information

Part Number	0348978240
Part Name	MINI50 RAHDR SMT 24CKT BLK POL A T&R
Part Information	

	Hazardous Substances					
Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
MINI50 RAHDR SMT 24CKT BLK POL A T&R	O	O	O	O	O	O
MINI50 HSNG RAHDR SMT 24CKT BLK POL A	O	O	O	O	O	O
MINI50 TERM SMT SOLDER NAIL LT MATTE SN	O	O	O	O	O	O
MINI50 TERM SMT SOLDER NAIL RT MATTE SN	O	O	O	O	O	O
MINI50 TERM BLD 0.50X15.57 MATTE SN	O	O	O	O	O	O
MINI50 TERM BLD 0.50X17.77 MATTE SN	O	O	O	O	O	O

Process Information

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A

Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Mar 5, 2021